

Electronic Patent Application Fee Transmittal

Application Number:	09741684			
Filing Date:	18-Dec-2000			
Title of Invention:	Bonding pad of suspension circuit			
First Named Inventor/Applicant Name:	Xm Wong			
Filer:	Sumit Bhattacharya/Barbara Vance			
Attorney Docket Number:	2855/29			
Filed as Large Entity				
Utility under 35 USC 111(a) Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Notice of appeal	1401	1	540	540
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				540